

Notice for TAIYO YUDEN products

Please read this notice before using the TAIYO YUDEN products.

REMINDERS

- Product information in this catalog is as of October 2011. All of the contents specified herein are subject to change without notice due to technical improvements, etc. Therefore, please check for the latest information carefully before practical application or usage of the Products.

Please note that Taiyo Yuden Co., Ltd. shall not be responsible for any defects in products or equipment incorporating such products, which are caused under the conditions other than those specified in this catalog or individual specification.

- Please contact Taiyo Yuden Co., Ltd. for further details of product specifications as the individual specification is available.
- Please conduct validation and verification of products in actual condition of mounting and operating environment before commercial shipment of the equipment.
- All electronic components or functional modules listed in this catalog are developed, designed and intended for use in general electronics equipment.(for AV, office automation, household, office supply, information service, telecommunications, (such as mobile phone or PC) etc.). Before incorporating the components or devices into any equipment in the field such as transportation,(automotive control, train control, ship control), transportation signal, disaster prevention, medical, public information network (telephone exchange, base station) etc. which may have direct influence to harm or injure a human body, please contact Taiyo Yuden Co., Ltd. for more detail in advance. Do not incorporate the products into any equipment in fields such as aerospace, aviation, nuclear control, submarine system, military, etc. where higher safety and reliability are especially required.

In addition, even electronic components or functional modules that are used for the general electronic equipment, if the equipment or the electric circuit require high safety or reliability function or performances, a sufficient reliability evaluation check for safety shall be performed before commercial shipment and moreover, due consideration to install a protective circuit is strongly recommended at customer's design stage.

- The contents of this catalog are applicable to the products which are purchased from our sales offices or distributors (so called "TAIYO YUDEN' s official sales channel").
It is only applicable to the products purchased from any of TAIYO YUDEN' s official sales channel.
- Please note that Taiyo Yuden Co., Ltd. shall have no responsibility for any controversies or disputes that may occur in connection with a third party's intellectual property rights and other related rights arising from your usage of products in this catalog. Taiyo Yuden Co., Ltd. grants no license for such rights.

- Caution for export
Certain items in this catalog may require specific procedures for export according to "Foreign Exchange and Foreign Trade Control Law" of Japan, "U.S. Export Administration Regulations", and other applicable regulations. Should you have any question or inquiry on this matter, please contact our sales staff.

STANDARD MULTILAYER CERAMIC CAPACITORS (TEMPERATURE COMPENSATING TYPE)



REFLOW

FEATURES

- Improved higher density mounting.
- Monolithic structure provides higher reliability.
- A wide range of capacitance values available in standard case sizes.

APPLICATIONS

- General electronic equipment
- Communication equipment (cellular phone, wireless applications, etc.)

PART NUMBER

U M K 1 0 5 △ C H 1 0 1 J V - F △

1 Rated voltage (VDC)

E	16
T	25
U	50

2 Series name

M	Multilayer ceramic capacitor
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3 End termination

K	Plated
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4 Dimension

Type	(inch)	L×W (mm)
042	(01005)	0.4×0.2
063	(0201)	0.6×0.3
105	(0402)	1.0×0.5

5 Dimension tolerance

△	Standard
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△=Blank space

6 Temperature characteristics (ppm/°C)

C□: 0	CH, CJ, CK	Tolerance
R□: -220	RH	H: ±60
S□: -330	SH, SJ, SK	J: ±120
T□: -470	TJ, TK	K: ±250
U□: -750	UJ, UK	
SL: +350~-1000		

□=Tolerance

7 Nominal capacitance (pF)

example	
0R5	0.5
010	1
100	10

※R=decimal point

8 Capacitance tolerance

C	±0.25pF
D	±0.5pF
F	±1pF
J	±5%
K	±10%

9 Thickness (mm)

C, D	0.2
T	0.3
V, W	0.5

10 Special code

-	Standard
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11 Packaging

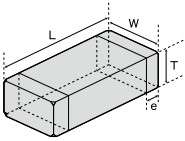
F	φ178mm Taping (2mm pitch)
W	φ178mm Taping (1mm pitch, 042 Type)

12 Internal code

△	Standard
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△=Blank space

STANDARD EXTERNAL DIMENSIONS/STANDARD QUANTITY



Type	Dimension [mm]				Standard quantity [pcs]	
	L	W	T	e	Paper tape	Embossed tape
□MK042 (01005 inch)	0.4±0.02	0.2±0.02	0.2±0.02	C, D	—	40000
□MK063 (0201 inch)	0.6±0.03	0.3±0.03	0.3±0.03	T	15000	—
□MK105 (0402 inch)	1.0±0.05	0.5±0.05	0.5±0.05	V, W	10000	—

AVAILABLE CAPACITANCE RANGE

Cap [pF]	Type	042		063		105				
		C□	C□	U□	C□	U□	SL	R□	S□	T□
		VDC		VDC		VDC				
[3-digit]	16V	50V	25V	50V						
0.5	0R5									
1	010									
1.5	1R5									
2	020									
3	030									
4	040									
5	050									
6	060	D								
7	070									
8	080									
9	090									
10	100									
12	120		T							
15	150									
18	180									
22	220									
27	270									
33	330									
39	390									
47	470									
56	560									
68	680									
82	820									
100	101									
120	121									
150	151									
180	181									
220	221									
270	271									
330	331									
390	391									
470	471									
560	561									
680	681									
820	821									
1000	102									

Note: Letters in the table indicate thickness.

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REPRESENTATIVE PART NUMBERS

●042TYPE

Class1 [C△ characteristic]

Rated voltage	Part number 1	Part number 2	Temp. char.	Capacitance (pF)	Capacitance tolerance	Q	Thickness (mm)	Soldering R:Reflow W:Wave	HALT	Internal code (P/N 1)	Note
									% Rated voltage		
16V	EMK042 CK0R5CD		CK	0.5	±0.25pF	410	0.2±0.02	R	200%		
	EMK042 CK010CD		CK	1	±0.25pF	420	0.2±0.02	R	200%		
	EMK042 CK1R5CD		CK	1.5	±0.25pF	430	0.2±0.02	R	200%		
	EMK042 CK020CD		CK	2	±0.25pF	440	0.2±0.02	R	200%		
	EMK042 CJ030CD		CJ	3	±0.25pF	460	0.2±0.02	R	200%		
	EMK042 CH040CD		CH	4	±0.25pF	480	0.2±0.02	R	200%		
	EMK042 CH050CD		CH	5	±0.25pF	500	0.2±0.02	R	200%		
	EMK042 CH060DD		CH	6	±0.5pF	520	0.2±0.02	R	200%		
	EMK042 CH070DD		CH	7	±0.5pF	540	0.2±0.02	R	200%		
	EMK042 CH080DD		CH	8	±0.5pF	560	0.2±0.02	R	200%		
	EMK042 CH090DD		CH	9	±0.5pF	580	0.2±0.02	R	200%		
	EMK042 CH100DD		CH	10	±0.5pF	600	0.2±0.02	R	200%		
	EMK042 CH120JD		CH	12	±5%	640	0.2±0.02	R	200%		
	EMK042 CH150JD		CH	15	±5%	700	0.2±0.02	R	200%		
	EMK042 CH180JC		CH	18	±5%	760	0.2±0.02	R	200%		
	EMK042 CH220JC		CH	22	±5%	840	0.2±0.02	R	200%		
	EMK042 CH270JC		CH	27	±5%	940	0.2±0.02	R	200%		
	EMK042 CH330JC		CH	33	±5%	1000	0.2±0.02	R	200%		
	EMK042 CH390JC		CH	39	±5%	1000	0.2±0.02	R	200%		
	EMK042 CH470JC		CH	47	±5%	1000	0.2±0.02	R	200%		
EMK042 CH560JC		CH	56	±5%	1000	0.2±0.02	R	200%			
EMK042 CH680JC		CH	68	±5%	1000	0.2±0.02	R	200%			
EMK042 CH820JC		CH	82	±5%	1000	0.2±0.02	R	200%			
EMK042 CH101JC		CH	100	±5%	1000	0.2±0.02	R	200%			

Note: Please contact Taiyo Yuden sales channels about items (capacitance and tolerance) other than listed above.

●063TYPE

Class1 [C△ characteristic]

Rated voltage	Part number 1	Part number 2	Temp. char.	Capacitance (pF)	Capacitance tolerance	Q	Thickness (mm)	Soldering R:Reflow W:Wave	HALT	Internal code (P/N 1)	Note
									% Rated voltage		
50V	UMK063 CK0R5CT		CK	0.5	±0.25pF	410	0.3±0.03	R	200%		
	UMK063 CK010CT		CK	1	±0.25pF	420	0.3±0.03	R	200%		
	UMK063 CK1R5CT		CK	1.5	±0.25pF	430	0.3±0.03	R	200%		
	UMK063 CK020CT		CK	2	±0.25pF	440	0.3±0.03	R	200%		
	UMK063 CJ030CT		CJ	3	±0.25pF	460	0.3±0.03	R	200%		
	UMK063 CH040CT		CH	4	±0.25pF	480	0.3±0.03	R	200%		
	UMK063 CH050CT		CH	5	±0.25pF	500	0.3±0.03	R	200%		
	UMK063 CH060DT		CH	6	±0.5pF	520	0.3±0.03	R	200%		
	UMK063 CH070DT		CH	7	±0.5pF	540	0.3±0.03	R	200%		
	UMK063 CH080DT		CH	8	±0.5pF	560	0.3±0.03	R	200%		
	UMK063 CH090DT		CH	9	±0.5pF	580	0.3±0.03	R	200%		
	UMK063 CH100DT		CH	10	±0.5pF	600	0.3±0.03	R	200%		
	UMK063 CH120JT		CH	12	±5%	640	0.3±0.03	R	200%		
	UMK063 CH150JT		CH	15	±5%	700	0.3±0.03	R	200%		
	UMK063 CH180JT		CH	18	±5%	760	0.3±0.03	R	200%		
	UMK063 CH220JT		CH	22	±5%	840	0.3±0.03	R	200%		
	UMK063 CH270JT		CH	27	±5%	940	0.3±0.03	R	200%		
	UMK063 CH330JT		CH	33	±5%	1000	0.3±0.03	R	200%		
	UMK063 CH390JT		CH	39	±5%	1000	0.3±0.03	R	200%		
	UMK063 CH470JT		CH	47	±5%	1000	0.3±0.03	R	200%		
UMK063 CH560JT		CH	56	±5%	1000	0.3±0.03	R	200%			
UMK063 CH680JT		CH	68	±5%	1000	0.3±0.03	R	200%			
UMK063 CH820JT		CH	82	±5%	1000	0.3±0.03	R	200%			
UMK063 CH101JT		CH	100	±5%	1000	0.3±0.03	R	200%			

Note: Please contact Taiyo Yuden sales channels about items (capacitance and tolerance) other than listed above.

Class1 [U△ characteristic]

Rated voltage	Part number 1	Part number 2	Temp. char.	Capacitance (pF)	Capacitance tolerance	Q	Thickness (mm)	Soldering R:Reflow W:Wave	HALT	Internal code (P/N 1)	Note
									% Rated voltage		
25V	TMK063 UK0R5CT		UK	0.5	±0.25pF	410	0.3±0.03	R	200%		
	TMK063 UK010CT		UK	1	±0.25pF	420	0.3±0.03	R	200%		
	TMK063 UK1R5CT		UK	1.5	±0.25pF	430	0.3±0.03	R	200%		
	TMK063 UK020CT		UK	2	±0.25pF	440	0.3±0.03	R	200%		
	TMK063 UK030CT		UK	3	±0.25pF	460	0.3±0.03	R	200%		
	TMK063 UJ040CT		UJ	4	±0.25pF	480	0.3±0.03	R	200%		
	TMK063 UJ050CT		UJ	5	±0.25pF	500	0.3±0.03	R	200%		
	TMK063 UJ060DT		UJ	6	±0.5pF	520	0.3±0.03	R	200%		
	TMK063 UJ070DT		UJ	7	±0.5pF	540	0.3±0.03	R	200%		
	TMK063 UJ080DT		UJ	8	±0.5pF	560	0.3±0.03	R	200%		
	TMK063 UJ090DT		UJ	9	±0.5pF	580	0.3±0.03	R	200%		
	TMK063 UJ100DT		UJ	10	±0.5pF	600	0.3±0.03	R	200%		
	TMK063 UJ120JT		UJ	12	±5%	640	0.3±0.03	R	200%		
	TMK063 UJ150JT		UJ	15	±5%	700	0.3±0.03	R	200%		

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REPRESENTATIVE PART NUMBERS

105TYPE

Class1 [C△ characteristic]

Rated voltage	Part number 1	Part number 2	Temp. char.	Capacitance [pF]	Capacitance tolerance	Q	Thickness [mm]	Soldering R:Reflow W:Wave	HALT	Internal code (P/N 1)	Note
									% Rated voltage		
50V	UMK105 CK0R5CV		CK	0.5	±0.25pF	410	0.5±0.05	R	200%		
	UMK105 CK010CV		CK	1	±0.25pF	420	0.5±0.05	R	200%		
	UMK105 CK1R5CV		CK	1.5	±0.25pF	430	0.5±0.05	R	200%		
	UMK105 CK020CV		CK	2	±0.25pF	440	0.5±0.05	R	200%		
	UMK105 CJ030CV		CJ	3	±0.25pF	460	0.5±0.05	R	200%		
	UMK105 CH040CV		CH	4	±0.25pF	480	0.5±0.05	R	200%		
	UMK105 CH050CV		CH	5	±0.25pF	500	0.5±0.05	R	200%		
	UMK105 CH060DV		CH	6	±0.5pF	520	0.5±0.05	R	200%		
	UMK105 CH070DV		CH	7	±0.5pF	540	0.5±0.05	R	200%		
	UMK105 CH080DV		CH	8	±0.5pF	560	0.5±0.05	R	200%		
	UMK105 CH090DV		CH	9	±0.5pF	580	0.5±0.05	R	200%		
	UMK105 CH100DV		CH	10	±0.5pF	600	0.5±0.05	R	200%		
	UMK105 CH120JV		CH	12	±5%	640	0.5±0.05	R	200%		
	UMK105 CH150JV		CH	15	±5%	700	0.5±0.05	R	200%		
	UMK105 CH180JV		CH	18	±5%	760	0.5±0.05	R	200%		
	UMK105 CH220JV		CH	22	±5%	840	0.5±0.05	R	200%		
	UMK105 CH270JV		CH	27	±5%	940	0.5±0.05	R	200%		
	UMK105 CH330JV		CH	33	±5%	1000	0.5±0.05	R	200%		
	UMK105 CH390JV		CH	39	±5%	1000	0.5±0.05	R	200%		
	UMK105 CH470JV		CH	47	±5%	1000	0.5±0.05	R	200%		
	UMK105 CH560JV		CH	56	±5%	1000	0.5±0.05	R	200%		
	UMK105 CH680JV		CH	68	±5%	1000	0.5±0.05	R	200%		
	UMK105 CH820JV		CH	82	±5%	1000	0.5±0.05	R	200%		
	UMK105 CH101JV		CH	100	±5%	1000	0.5±0.05	R	200%		
	UMK105 CH121JV		CH	120	±5%	1000	0.5±0.05	R	200%		
	UMK105 CH151JV		CH	150	±5%	1000	0.5±0.05	R	200%		
	UMK105 CH181JV		CH	180	±5%	1000	0.5±0.05	R	200%		
	UMK105 CH221JV		CH	220	±5%	1000	0.5±0.05	R	200%		
	UMK105 CH271JV		CH	270	±5%	1000	0.5±0.05	R	200%		
	UMK105 CH331JV		CH	330	±5%	1000	0.5±0.05	R	200%		

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Class1 [U△ characteristic]

Rated voltage	Part number 1	Part number 2	Temp. char.	Capacitance [pF]	Capacitance tolerance	Q	Thickness [mm]	Soldering R:Reflow W:Wave	HALT	Internal code (P/N 1)	Note
									% Rated voltage		
50V	UMK105 UK0R5CV		UK	0.5	±0.25pF	410	0.5±0.05	R	200%		
	UMK105 UK010CV		UK	1	±0.25pF	420	0.5±0.05	R	200%		
	UMK105 UK1R5CV		UK	1.5	±0.25pF	430	0.5±0.05	R	200%		
	UMK105 UK020CV		UK	2	±0.25pF	440	0.5±0.05	R	200%		
	UMK105 UK030CV		UK	3	±0.25pF	460	0.5±0.05	R	200%		
	UMK105 UJ040CV		UJ	4	±0.25pF	480	0.5±0.05	R	200%		
	UMK105 UJ050CV		UJ	5	±0.25pF	500	0.5±0.05	R	200%		
	UMK105 UJ060DV		UJ	6	±0.5pF	520	0.5±0.05	R	200%		
	UMK105 UJ070DV		UJ	7	±0.5pF	540	0.5±0.05	R	200%		
	UMK105 UJ080DV		UJ	8	±0.5pF	560	0.5±0.05	R	200%		
	UMK105 UJ090DV		UJ	9	±0.5pF	580	0.5±0.05	R	200%		
	UMK105 UJ100DV		UJ	10	±0.5pF	600	0.5±0.05	R	200%		
	UMK105 UJ120JV		UJ	12	±5%	640	0.5±0.05	R	200%		
	UMK105 UJ150JV		UJ	15	±5%	700	0.5±0.05	R	200%		
	UMK105 UJ180JV		UJ	18	±5%	760	0.5±0.05	R	200%		
	UMK105 UJ220JV		UJ	22	±5%	840	0.5±0.05	R	200%		
	UMK105 UJ270JV		UJ	27	±5%	940	0.5±0.05	R	200%		
	UMK105 UJ330JV		UJ	33	±5%	1000	0.5±0.05	R	200%		
	UMK105 UJ390JV		UJ	39	±5%	1000	0.5±0.05	R	200%		
	UMK105 UJ470JV		UJ	47	±5%	1000	0.5±0.05	R	200%		
	UMK105 UJ560JV		UJ	56	±5%	1000	0.5±0.05	R	200%		
	UMK105 UJ680JV		UJ	68	±5%	1000	0.5±0.05	R	200%		
	UMK105 UJ820JV		UJ	82	±5%	1000	0.5±0.05	R	200%		
	UMK105 UJ101JV		UJ	100	±5%	1000	0.5±0.05	R	200%		
	UMK105 UJ121JV		UJ	120	±5%	1000	0.5±0.05	R	200%		
	UMK105 UJ151JV		UJ	150	±5%	1000	0.5±0.05	R	200%		
	UMK105 UJ181JV		UJ	180	±5%	1000	0.5±0.05	R	200%		
	UMK105 UJ221JV		UJ	220	±5%	1000	0.5±0.05	R	200%		
	UMK105 UJ271JV		UJ	270	±5%	1000	0.5±0.05	R	200%		
	UMK105 UJ331JV		UJ	330	±5%	1000	0.5±0.05	R	200%		

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REPRESENTATIVE PART NUMBERS

Class1 [SL characteristic]

Rated voltage	Part number 1	Part number 2	Temp. char.	Capacitance (pF)	Capacitance tolerance	Q	Thickness (mm)	Soldering R:Reflow W:Wave	HALT	Internal code (P/N 1)	Note
									% Rated voltage		
50V	UMK105 SL121JV		SL	120	±5%	1000	0.5±0.05	R	200%		
	UMK105 SL151JV		SL	150	±5%	1000	0.5±0.05	R	200%		
	UMK105 SL181JV		SL	180	±5%	1000	0.5±0.05	R	200%		
	UMK105 SL221JV		SL	220	±5%	1000	0.5±0.05	R	200%		
	UMK105 SL271JV		SL	270	±5%	1000	0.5±0.05	R	200%		
	UMK105 SL331JV		SL	330	±5%	1000	0.5±0.05	R	200%		

Note: Please contact Taiyo Yuden sales channels about items (capacitance and tolerance) other than listed above.

Class1 [RH characteristic]

Rated voltage	Part number 1	Part number 2	Temp. char.	Capacitance (pF)	Capacitance tolerance	Q	Thickness (mm)	Soldering R:Reflow W:Wave	HALT	Internal code (P/N 1)	Note
									% Rated voltage		
50V	UMK105 RH5R6JW		RH	5.6	±5%	512	0.5±0.05	R	200%		
	UMK105 RH6R8JW		RH	6.8	±5%	536	0.5±0.05	R	200%		
	UMK105 RH8R2JW		RH	8.2	±5%	564	0.5±0.05	R	200%		
	UMK105 RH100JW		RH	10	±5%	600	0.5±0.05	R	200%		
	UMK105 RH120JW		RH	12	±5%	640	0.5±0.05	R	200%		
	UMK105 RH150JW		RH	15	±5%	700	0.5±0.05	R	200%		
	UMK105 RH180JW		RH	18	±5%	760	0.5±0.05	R	200%		
	UMK105 RH200JW		RH	20	±5%	800	0.5±0.05	R	200%		

Note: Please contact Taiyo Yuden sales channels about items (capacitance and tolerance) other than listed above.

Class1 [S△ characteristic]

Rated voltage	Part number 1	Part number 2	Temp. char.	Capacitance (pF)	Capacitance tolerance	Q	Thickness (mm)	Soldering R:Reflow W:Wave	HALT	Internal code (P/N 1)	Note
									% Rated voltage		
50V	UMK105 SK0R5BW		SK	0.5	±0.1pF	410	0.5±0.05	R	200%		
	UMK105 SK010BW		SK	1	±0.1pF	420	0.5±0.05	R	200%		
	UMK105 SK1R2BW		SK	1.2	±0.1pF	424	0.5±0.05	R	200%		
	UMK105 SK1R5BW		SK	1.5	±0.1pF	430	0.5±0.05	R	200%		
	UMK105 SK1R8BW		SK	1.8	±0.1pF	436	0.5±0.05	R	200%		
	UMK105 SK2R2JW		SK	2.2	±5%	444	0.5±0.05	R	200%		
	UMK105 SK2R7JW		SK	2.7	±5%	454	0.5±0.05	R	200%		
	UMK105 SJ3R3JW		SJ	3.3	±5%	466	0.5±0.05	R	200%		
	UMK105 SJ3R9JW		SJ	3.9	±5%	478	0.5±0.05	R	200%		
	UMK105 SH4R7JW		SH	4.7	±5%	494	0.5±0.05	R	200%		
	UMK105 SH5R6JW		SH	5.6	±5%	512	0.5±0.05	R	200%		
	UMK105 SH6R8JW		SH	6.8	±5%	536	0.5±0.05	R	200%		
	UMK105 SH8R2JW		SH	8.2	±5%	564	0.5±0.05	R	200%		
	UMK105 SH100JW		SH	10	±5%	600	0.5±0.05	R	200%		
	UMK105 SH120JW		SH	12	±5%	640	0.5±0.05	R	200%		
	UMK105 SH150JW		SH	15	±5%	700	0.5±0.05	R	200%		
	UMK105 SH180JW		SH	18	±5%	760	0.5±0.05	R	200%		
	UMK105 SH200JW		SH	20	±5%	800	0.5±0.05	R	200%		

Note: Please contact Taiyo Yuden sales channels about items (capacitance and tolerance) other than listed above.

Class1 [T△ characteristic]

Rated voltage	Part number 1	Part number 2	Temp. char.	Capacitance (pF)	Capacitance tolerance	Q	Thickness (mm)	Soldering R:Reflow W:Wave	HALT	Internal code (P/N 1)	Note
									% Rated voltage		
50V	UMK105 TK0R5BW		TK	0.5	±0.1pF	410	0.5±0.05	R	200%		
	UMK105 TK010BW		TK	1	±0.1pF	420	0.5±0.05	R	200%		
	UMK105 TK1R2BW		TK	1.2	±0.1pF	424	0.5±0.05	R	200%		
	UMK105 TK1R5BW		TK	1.5	±0.1pF	430	0.5±0.05	R	200%		
	UMK105 TK1R8BW		TK	1.8	±0.1pF	436	0.5±0.05	R	200%		
	UMK105 TK2R2JW		TK	2.2	±5%	444	0.5±0.05	R	200%		
	UMK105 TK2R7JW		TK	2.7	±5%	454	0.5±0.05	R	200%		
	UMK105 TK3R3JW		TK	3.3	±5%	466	0.5±0.05	R	200%		
	UMK105 TK3R9JW		TK	3.9	±5%	478	0.5±0.05	R	200%		
	UMK105 TJ4R7JW		TJ	4.7	±5%	494	0.5±0.05	R	200%		
	UMK105 TJ5R6JW		TJ	5.6	±5%	512	0.5±0.05	R	200%		
	UMK105 TJ6R8JW		TJ	6.8	±5%	536	0.5±0.05	R	200%		
	UMK105 TJ8R2JW		TJ	8.2	±5%	564	0.5±0.05	R	200%		
	UMK105 TJ100JW		TJ	10	±5%	600	0.5±0.05	R	200%		
	UMK105 TJ120JW		TJ	12	±5%	640	0.5±0.05	R	200%		
	UMK105 TJ150JW		TJ	15	±5%	700	0.5±0.05	R	200%		
	UMK105 TJ180JW		TJ	18	±5%	760	0.5±0.05	R	200%		
	UMK105 TJ200JW		TJ	20	±5%	800	0.5±0.05	R	200%		

Note: Please contact Taiyo Yuden sales channels about items (capacitance and tolerance) other than listed above.

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PACKAGING

① Minimum Quantity

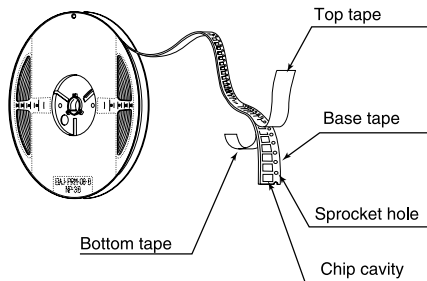
● Taped package

Type	Thickness		Standard quantity [pcs]		
	mm	code	Paper tape	Embossed tape	
□MK042	0.2	C, D	—	40000	
□MK063	0.3	P, T	15000	—	
□2K096	0.3	P	10000		
	0.45	K			
□WK105	0.3	P	20000		
□MK105	0.2	C			
	0.3	P			
□VK105	0.5	V, W	10000		
	0.45	K			
□MK107	0.5	V	—		4000
□WK107	0.8	A	—		
□2K110	0.5	V	4000	—	
	0.6	B			
	0.8	A			
□MK212	0.45	K	—	—	
	0.85	D			
□WK212	1.25	G	—	3000	
□4K212	0.85	D	4000	—	
□2K212	0.85	D			
□MK316	1.15	F			—
	1.25	G			
	1.6	L			
	0.85	D			
□MK325	1.15	F	—	2000	
	1.9	N			
	2.0max	Y			
	2.5	M			
□MK432	2.5	M	—	500(T), 1000(P)	
			—	500	

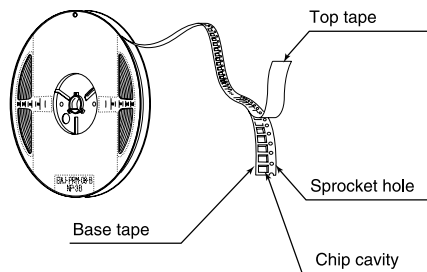
② Taping material

※ No bottom tape for pressed carrier tape

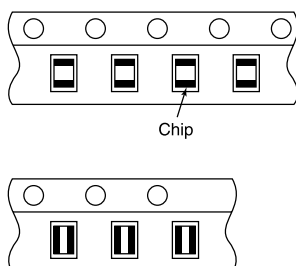
● Paper tape



● Embossed tape



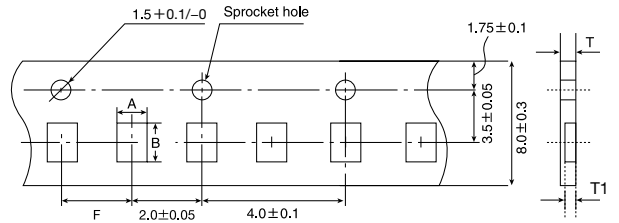
● Chip filled



③ Representative taping dimensions

● Paper Tape (8mm wide)

● Pressed carrier tape (2mm pitch)

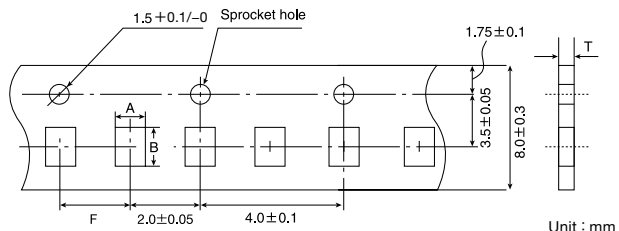


Unit : mm

Type	Chip Cavity		Insertion Pitch F	Tape Thickness	
	A	B		T	T1
□MK063	0.37	0.67	2.0±0.05	0.45max.	0.42max.
□2K096	0.65	1.02			
□WK105	0.65	1.15		0.4max.	0.3max.
MK105(+C)				0.45max.	0.42max.

* Thickness, C : 0.2mm, P : 0.3mm

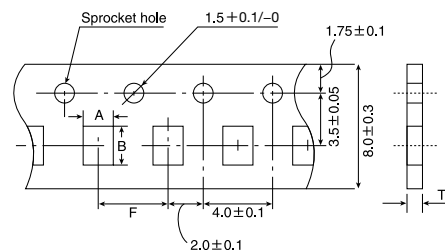
● Punched carrier tape (2mm pitch)



Unit : mm

Type	Chip Cavity		Insertion Pitch F	Tape Thickness
	A	B		T
□2K096	0.72	1.02	2.0±0.05	0.6max.
□MK105	0.65	1.15		0.8max.
□VK105				

● Punched carrier tape (4mm pitch)



Unit : mm

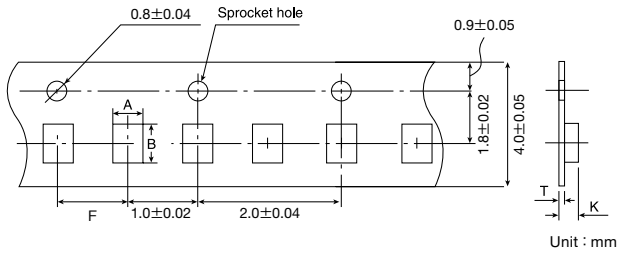
Type	Chip Cavity		Insertion Pitch F	Tape Thickness
	A	B		T
□MK107	1.0	1.8	4.0±0.1	1.1max.
□WK107				
□2K110	1.15	1.55		1.0max.
□MK212	1.65	2.4		1.1max.
□WK212				
□4K212	2.0	3.6		
□2K212				
□MK316				

Note : Taping size might be different depending on the size of the product.

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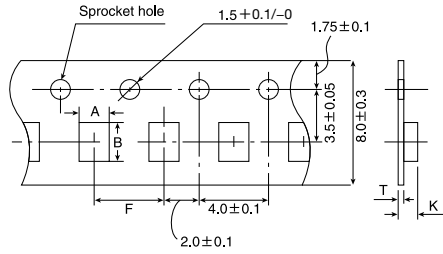
● Embossed tape (4mm wide)



Unit : mm

Type	Chip Cavity		Insertion Pitch F	Tape Thickness	
	A	B		K	T
□MK042	0.23	0.43	1.0±0.02	0.5max.	0.25max.

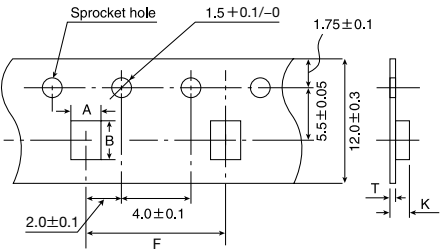
● Embossed tape (8mm wide)



Unit : mm

Type	Chip Cavity		Insertion Pitch F	Tape Thickness	
	A	B		K	T
□WK107	1.0	1.8	4.0±0.1	1.3max	0.25±0.1
□MK212	1.65	2.4		3.4max.	0.6max.
□MK316	2.0	3.6			
□MK325	2.8	3.6			

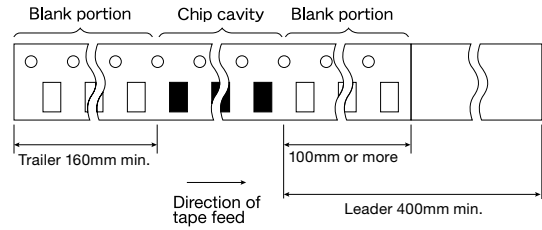
● Embossed tape (12mm wide)



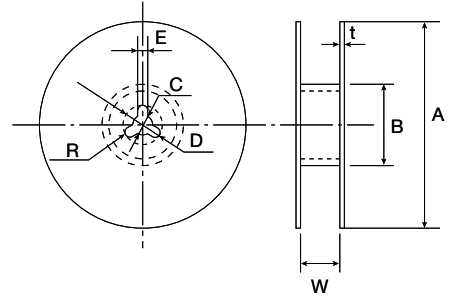
Unit : mm

Type	Chip Cavity		Insertion Pitch F	Tape Thickness	
	A	B		K	T
□MK432	3.7	4.9	8.0±0.1	4.0max.	0.6max.

④ Trailer and Leader



⑤ Reel size

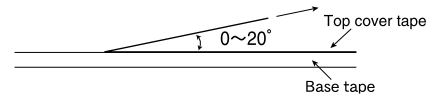


Unit : mm

A	B	C
φ178±2.0	φ50min.	φ13.0±0.2
D	E	R
φ21.0±0.8	2.0±0.5	1.0
	t	W
4mm wide tape	1.5max.	5±1.0
8mm wide tape	2.5max.	10±1.5
12mm wide tape	2.5max.	14±1.5

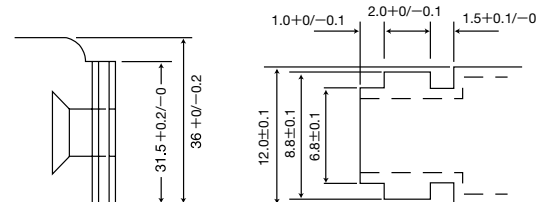
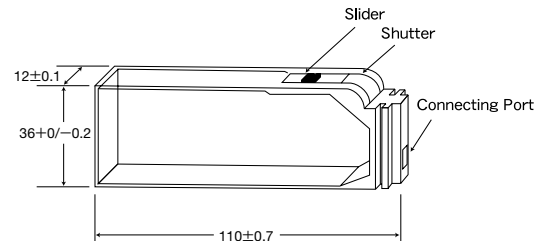
⑥ Top Tape Strength

The top tape requires a peel-off force of 0.1 to 0.7N in the direction of the arrow as illustrated below.



⑦ Bulk Cassette

The exchange of individual specification is necessary. Please contact Taiyo Yuden sales channels.



Unit : mm

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Super Low Distortion Multilayer Ceramic Capacitors and Medium-High Voltage Multilayer Ceramic Capacitors are noted separately.

Multilayer Ceramic Capacitors

1. Operating Temperature Range				
Specified Value	Temperature Compensating (Class 1)	Standard	-55 to +125°C	
		High Frequency Type		
	High Permittivity (Class 2)		Specification	Temperature Range
			BJ	B -25 to +85°C X5R -55 to +85°C
			B7	X7R -55 to +125°C
			C6	X6S -55 to +105°C
			C7	X7S -55 to +125°C
			F	F -25 to +85°C Y5V -30 to +85°C
2. Storage Conditions				
Specified Value	Temperature Compensating (Class 1)	Standard	-55 to +125°C	
		High Frequency Type		
	High Permittivity (Class 2)		Specification	Temperature Range
			BJ	B -25 to +85°C X5R -55 to +85°C
			B7	X7R -55 to +125°C
			C6	X6S -55 to +105°C
			C7	X7S -55 to +125°C
			F	F -25 to +85°C Y5V -30 to +85°C
3. Rated Voltage				
Specified Value	Temperature Compensating (Class 1)	Standard	50VDC, 25VDC, 16VDC	
		High Frequency Type	50VDC, 16VDC	
	High Permittivity (Class 2)		50VDC, 35VDC, 25VDC, 16VDC, 10VDC, 6.3VDC, 4VDC	
4. Withstanding Voltage (Between terminals)				
Specified Value	Temperature Compensating (Class 1)	Standard	No breakdown or damage	
		High Frequency Type		
	High Permittivity (Class 2)			
[Test Methods and Remarks]				
		Class 1	Class 2	
	Applied voltage	Rated voltage×3	Rated voltage×2.5	
	Duration	1 to 5 sec.		
	Charge/discharge current	50mA max.		
5. Insulation Resistance				
Specified Value	Temperature Compensating (Class 1)	Standard	10000 MΩ min.	
		High Frequency Type		
	High Permittivity (Class 2) Note 1		C≤0.047μF : 10000 MΩ min. C>0.047μF : 500MΩ·μF	
[Test Methods and Remarks]				
Applied voltage: Rated voltage				
Duration: 60±5 sec.				
Charge/discharge current: 50mA max.				
6. Capacitance (Tolerance)				
Specified Value	Temperature Compensating (Class 1)	Standard	C△ 0.5pF≤C≤5pF : ±0.25pF U△ 0.5pF<C≤10pF : ±0.5pF C>10pF : ±5%	RH 0.5pF≤C≤2pF : ±0.1pF S△ C>2pF : ±5% T△ C>2pF : ±5%
		High Frequency Type	CH 0.5pF≤C≤2pF : ±0.1pF RH C>2pF : ±5%	
	High Permittivity (Class 2)		BJ, B7, C6,C7 : ±10% or ±20%, F : -20%/+80%	
[Test Methods and Remarks]				
		Class 1	Class 2	
		Standard	High Frequency Type	C≤10μF C>10μF
	Preconditioning	None		Thermal treatment (at 150°C for 1hr) Note 2
	Measuring frequency	1MHz±10%		1kHz±10% 120±10Hz
	Measuring voltage Note 1	0.5 to 5Vrms		1±0.2Vrms 0.5±0.1Vrms
	Bias application	None		
7. Q or Dissipation Factor				
Specified Value	Temperature Compensating (Class 1)	Standard	C<30 pF : Q≥400+20C, C≥30 pF : Q≥1000 (C : Nominal capacitance)	
		High Frequency Type	Refer to detailed specification	
	High Permittivity (Class 2) Note 1		BJ, B7, C6,C7 : 2.5% max., F : 7% max.	
[Test Methods and Remarks]				
		Class 1	Class 2	
		Standard	High Frequency Type	C≤10μF C>10μF
	Preconditioning	None		Thermal treatment (at 150°C for 1hr) Note 2
	Measuring frequency	1MHz±10%	1GHz	1kHz±10% 120±10Hz
	Measuring voltage Note 1	0.5 to 5Vrms		1±0.2Vrms 0.5±0.1Vrms
	Bias application	None		

High Frequency Type
Measuring equipment: HP4291A
Measuring jig: HP16192A

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RELIABILITY DATA

8. Temperature Characteristic (Without voltage application)

Specified Value	Temperature Compensating (Class 1)	Standard	Temperature Characteristic [ppm/°C]		Tolerance H±60 J±120 K±250	
		High Frequency Type	C□ : 0	CH, CJ, CK		
			R□ : -220	RH		
			S□ : -330	SH, SJ, SK		
			T□ : -470	TJ, TK		
			U□ : -750	UJ, UK		
			SL : +350 to -1000			
Specified Value	High Permittivity (Class 2)		Specification	Capacitance change	Reference temperature	Temperature Range
		BJ	B	±10%	20°C	-25 to +85°C
			X5R	±15%	25°C	-55 to +85°C
		B7	X7R	±15%	25°C	-55 to +125°C
			X6S	±22%	25°C	-55 to +105°C
		C7	X7S	±22%	25°C	-55 to +125°C
			F	+30/-80%	20°C	-25 to +85°C
	Y5V	+22/-82%	25°C	-30 to +85°C		

[Test Methods and Remarks]

Class 1

Capacitance at 20°C and 85°C shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation.

$$\frac{(C_{85}-C_{20})}{C_{20} \times \Delta T} \times 10^6 \text{ (ppm/°C)} \quad \Delta T=65$$

Class 2

Capacitance at each step shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation.

Step	B, F	X5R, X7R, X6S, X7S, Y5V	$\frac{(C-C_2)}{C_2} \times 100(\%)$
1	Minimum operating temperature		C : Capacitance in Step 1 or Step 3 C ₂ : Capacitance in Step 2
2	20°C	25°C	
3	Maximum operating temperature		

9. Deflection

Specified Value	Temperature Compensating (Class 1)	Standard	Appearance : No abnormality Capacitance change : Within ±5% or ±0.5 pF, whichever is larger.
		High Frequency Type	Appearance : No abnormality Capacitance change : Within ±0.5 pF
	High Permittivity (Class 2)		Appearance : No abnormality Capacitance change : Within ±12.5% (BJ, B7, C6, C7), Within ±30% (F)

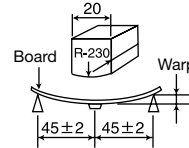
[Test Methods and Remarks]

Multilayer Ceramic Capacitors

	Board	Thickness	Warp	Duration
042, 063 Type	glass epoxy-resin substrate	0.8mm	1mm	10 sec.
The other types		1.6mm		

Array Type

	Board	Thickness	Warp	Duration
096, 110, 212 Type	glass epoxy-resin substrate	1.6mm	1mm	10 sec.



Capacitance measurement shall be conducted with the board bent (Unit: mm)

10. Body Strength

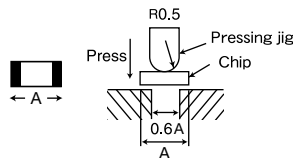
Specified Value	Temperature Compensating (Class 1)	Standard	—
		High Frequency Type	No mechanical damage.
	High Permittivity (Class 2)		—

[Test Methods and Remarks]

High Frequency Type

Applied force: 5N

Duration: 10 sec.



11. Adhesive Strength of Terminal Electrodes

Specified Value	Temperature Compensating (Class 1)	Standard	No terminal separation or its indication.
		High Frequency Type	
	High Permittivity (Class 2)		

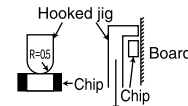
[Test Methods and Remarks]

Multilayer Ceramic Capacitors

	Applied force	Duration
042, 063 Type	2N	30±5 sec.
105 Type or more	5N	

Array Type

	Applied force	Duration
096 Type	2N	30±5 sec.
110, 212 Type	5N	



12. Solderability

Specified Value	Temperature Compensating (Class 1)	Standard	At least 95% of terminal electrode is covered by new solder.
		High Frequency Type	
	High Permittivity (Class 2)		

[Test Methods and Remarks]

	Solder type	Solder temperature	Duration
Eutectic solder	H60A or H63A	230±5°C	4±1 sec.
	Lead-free solder	Sn-3.0Ag-0.5Cu	

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RELIABILITY DATA

13. Resistance to Soldering

Specified Value	Temperature Compensating (Class 1)	Standard	Appearance: No abnormality Capacitance change: Within $\pm 2.5\%$ or $\pm 0.25\text{pF}$, whichever is larger. Q: Initial value Insulation resistance: Initial value Withstanding voltage (between terminals): No abnormality
		High Frequency Type	Appearance: No abnormality Capacitance change: Within $\pm 2.5\%$ Q: Initial value Insulation resistance: Initial value Withstanding voltage (between terminals): No abnormality
	High Permittivity (Class 2) Note 1	Appearance: No abnormality Capacitance change: Within $\pm 7.5\%$ (BJ, B7, C6, C7) Within $\pm 20\%$ (F) Dissipation factor: Initial value Insulation resistance: Initial value Withstanding voltage (between terminals): No abnormality	

[Test Methods and Remarks]

Class 1			Class 2			
	042, 063 Type	105 Type Array (096, 110 Type)		042, 063 Type	105, 107, 212 Type Array (096, 110, 212 Type)	316, 325 Type
Preconditioning	None		Preconditioning	Thermal treatment (at 150°C for 1 hr) Note 2		
Preheating	150°C, 1 to 2 min.	80 to 100°C, 2 to 5 min. 150 to 200°C, 2 to 5 min.	Preheating	150°C, 1 to 2 min.	80 to 100°C, 2 to 5 min. 150 to 200°C, 2 to 5 min.	80 to 100°C, 5 to 10 min. 150 to 200°C, 5 to 10 min.
Solder temp.	270 \pm 5°C		Solder temp.	270 \pm 5°C		
Duration	3 \pm 0.5 sec.		Duration	3 \pm 0.5 sec.		
Recovery	6 to 24 hrs (Standard condition) Note 5		Recovery	24 \pm 2 hrs (Standard condition) Note 5		

14. Temperature Cycle (Thermal Shock)

Specified Value	Temperature Compensating (Class 1)	Standard	Appearance: No abnormality Capacitance change: Within $\pm 2.5\%$ or $\pm 0.25\text{pF}$, whichever is larger. Q: Initial value Insulation resistance: Initial value Withstanding voltage (between terminals): No abnormality
		High Frequency Type	Appearance: No abnormality Capacitance change: Within $\pm 0.25\text{pF}$ Q: Initial value Insulation resistance: Initial value Withstanding voltage (between terminals): No abnormality
	High Permittivity (Class 2) Note 1	Appearance: No abnormality Capacitance change: Within $\pm 7.5\%$ (BJ, B7, C6, C7) Within $\pm 20\%$ (F) Dissipation factor: Initial value Insulation resistance: Initial value Withstanding voltage (between terminals): No abnormality	

[Test Methods and Remarks]

	Class 1		Class 2	
Preconditioning	None		Thermal treatment (at 150°C for 1 hr) Note 2	
1 cycle	Step	Temperature (°C)	Time (min.)	
	1	Lowest operating temperature +0/-3	30 \pm 3	
	2	Normal temperature	2 to 3	
	3	Highest operating temperature +0/-3	30 \pm 3	
	4	Normal temperature	2 to 3	
Number of cycles	5 times			
Recovery	6 to 24 hrs (Standard condition) Note 5		24 \pm 2 hrs (Standard condition) Note 5	

15. Humidity (Steady State)

Specified Value	Temperature Compensating (Class 1)	Standard	Appearance: No abnormality Capacitance change: Within $\pm 5\%$ or $\pm 0.5\text{pF}$, whichever is larger. Q: C < 10pF : Q \geq 200+10C 10 \leq C < 30pF : Q \geq 275+2.5C C \geq 30pF : Q \geq 350 (C : Nominal capacitance) Insulation resistance: 1000 M Ω min.
		High Frequency Type	Appearance: No abnormality Capacitance change: Within $\pm 0.5\text{pF}$ Insulation resistance: 1000 M Ω min.
	High Permittivity (Class 2) Note 1	Appearance: No abnormality Capacitance change: Within $\pm 12.5\%$ (BJ, B7, C6, C7) Within $\pm 30\%$ (F) Dissipation factor : 5.0% max. (BJ, B7, C6, C7) 11.0% max. (F) Insulation resistance: 50 M $\Omega\mu\text{F}$ or 1000 M Ω whichever is smaller.	

[Test Methods and Remarks]

Class 1			Class 2	
	Standard	High Frequency Type	All items	
Preconditioning	None		Preconditioning	Thermal treatment (at 150°C for 1 hr) Note 2
Temperature	40 \pm 2°C	60 \pm 2°C	Temperature	40 \pm 2°C
Humidity	90 to 95%RH		Humidity	90 to 95%RH
Duration	500+24/-0 hrs		Duration	500+24/-0 hrs
Recovery	6 to 24 hrs (Standard condition) Note 5		Recovery	24 \pm 2 hrs (Standard condition) Note 5

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RELIABILITY DATA

16. Humidity Loading

Specified Value	Temperature Compensating (Class 1)	Standard	Appearance: No abnormality Capacitance change: Within $\pm 7.5\%$ or $\pm 0.75\text{pF}$, whichever is larger. Q : $C < 30\text{pF} : Q \geq 100 + 10C/3$ $C \geq 30\text{pF} : Q \geq 200$ (C : Nominal capacitance) Insulation resistance: 500 M Ω min.
		High Frequency Type	Appearance: No abnormality Capacitance change: $C \leq 2\text{pF} : \text{Within } \pm 0.4 \text{ pF}$ $C > 2\text{pF} : \text{Within } \pm 0.75 \text{ pF}$ (C : Nominal capacitance) Insulation resistance: 500 M Ω min.
	High Permittivity (Class 2) Note 1	Appearance: No abnormality Capacitance change: Within $\pm 12.5\%$ (BJ, B7, C6, C7) Within $\pm 30\%$ (F) Dissipation factor : 5.0% max. (BJ, B7, C6, C7) 11.0% max. (F) Insulation resistance: 25 M $\Omega\mu\text{F}$ or 500 M Ω , whichever is smaller.	

[Test Methods and Remarks]

Class 1

	Standard	High Frequency Type
Preconditioning	None	
Temperature	40 \pm 2 $^{\circ}\text{C}$	60 \pm 2 $^{\circ}\text{C}$
Humidity	90 to 95%RH	
Duration	500+24/-0 hrs	
Applied voltage	Rated voltage	
Charge/discharge current	50mA max.	
Recovery	6 to 24 hrs (Standard condition) Note 5	

Class 2

	All items
Preconditioning	Voltage treatment (Rated voltage are applied for 1 hour at 40 $^{\circ}\text{C}$) Note 3
Temperature	40 \pm 2 $^{\circ}\text{C}$
Humidity	90 to 95%RH
Duration	500+24/-0 hrs
Applied voltage	Rated voltage
Charge/discharge current	50mA max.
Recovery	24 \pm 2 hrs (Standard condition) Note 5

17. High Temperature Loading

Specified Value	Temperature Compensating (Class 1)	Standard	Appearance: No abnormality Capacitance change: Within $\pm 3\%$ or $\pm 0.3\text{pF}$, whichever is larger. Q : $C < 10\text{pF} : Q \geq 200 + 10C$ $10 \leq C < 30\text{pF} : Q \geq 275 + 2.5C$ $C \geq 30\text{pF} : Q \geq 350$ (C : Nominal capacitance) Insulation resistance: 1000 M Ω min.
		High Frequency Type	Appearance: No abnormality Capacitance change: Within $\pm 3\%$ or $\pm 0.3\text{pF}$, whichever is larger. Insulation resistance: 1000 M Ω min.
	High Permittivity (Class 2) Note 1	Appearance: No abnormality Capacitance change: Within $\pm 12.5\%$ (BJ, B7, C6, C7) Within $\pm 30\%$ (F) Dissipation factor : 5.0% max. (BJ, B7, C6, C7) 11.0% max. (F) Insulation resistance: 50 M $\Omega\mu\text{F}$ or 1000 M Ω , whichever is smaller.	

[Test Methods and Remarks]

Class 1

	Standard	High Frequency Type
Preconditioning	None	
Temperature	125 \pm 3 $^{\circ}\text{C}$	
Duration	1000+48/-0 hrs	
Applied voltage	Rated voltage \times 2	
Charge/discharge current	50mA max.	
Recovery	6 to 24hr (Standard condition) Note 5	

Class 2

	BJ, F	C6	B7, C7
Preconditioning	Voltage treatment (Twice the rated voltage shall be applied for 1 hour at 85 $^{\circ}\text{C}$, 105 $^{\circ}\text{C}$ or 125 $^{\circ}\text{C}$) Note 3, 4		
Temperature	85 \pm 2 $^{\circ}\text{C}$	105 \pm 3 $^{\circ}\text{C}$	125 \pm 3 $^{\circ}\text{C}$
Duration	1000+48/-0 hrs		
Applied voltage	Rated voltage \times 2 Note 4		
Charge/discharge current	50mA max.		
Recovery	24 \pm 2 hrs (Standard condition) Note 5		

Note 1 The figures indicate typical specifications. Please refer to individual specifications in detail.

Note 2 Thermal treatment : Initial value shall be measured after test sample is heat-treated at 150+0/-10 $^{\circ}\text{C}$ for an hour and kept at room temperature for 24 \pm 2hours.

Note 3 Voltage treatment : Initial value shall be measured after test sample is voltage-treated for an hour at both the temperature and voltage specified in the test conditions, and kept at room temperature for 24 \pm 2hours.

Note 4 150% of rated voltage is applicable to some items. Please refer to their specifications for further information.

Note 5 Standard condition: Temperature: 5 to 35 $^{\circ}\text{C}$, Relative humidity: 45 to 85 % RH, Air pressure: 86 to 106kPa
When there are questions concerning measurement results, in order to provide correlation data, the test shall be conducted under the following condition.

Temperature: 20 \pm 2 $^{\circ}\text{C}$, Relative humidity: 60 to 70 % RH, Air pressure: 86 to 106kPa
Unless otherwise specified, all the tests are conducted under the "standard condition".

PRECAUTIONS

Precautions on the use of Multilayer Ceramic Capacitors

1. Circuit Design

- ◆ Verification of operating environment, electrical rating and performance
 1. A malfunction of equipment in fields such as medical, aerospace, nuclear control, etc. may cause serious harm to human life or have severe social ramifications. Therefore, any capacitors to be used in such equipment may require higher safety and reliability, and shall be clearly differentiated from them used in general purpose applications.
- ◆ Operating Voltage (Verification of Rated voltage)
 1. The operating voltage for capacitors must always be their rated voltage or less.
 If an AC voltage is loaded on a DC voltage, the sum of the two peak voltages shall be the rated voltage or less.
 For a circuit where an AC or a pulse voltage may be used, the sum of their peak voltages shall also be the rated voltage or less.
2. Even if an applied voltage is the rated voltage or less reliability of capacitors may be deteriorated in case that either a high frequency AC voltage or a pulse voltage having rapid rise time is used in a circuit.

2. PCB Design

- ◆ Pattern configurations (Design of Land-patterns)
 1. When capacitors are mounted on PCBs, the amount of solder used (size of fillet) can directly affect the capacitor performance. Therefore, the following items must be carefully considered in the design of land patterns:
 (1) Excessive solder applied can cause mechanical stresses which lead to chip breaking or cracking. Therefore, please consider appropriate land-patterns for proper amount of solder.
 (2) When more than one component are jointly soldered onto the same land, each component's soldering point shall be separated by solder-resist.
- ◆ Pattern configurations (Capacitor layout on PCBs)
 After capacitors are mounted on boards, they can be subjected to mechanical stresses in subsequent manufacturing processes (PCB cutting, board inspection, mounting of additional parts, assembly into the chassis, wave soldering of the boards, etc.). For this reason, land pattern configurations and positions of capacitors shall be carefully considered to minimize stresses.

- ◆ Pattern configurations (Design of Land-patterns)
 The following diagrams and tables show some examples of recommended land patterns to prevent excessive solder amounts.

(1) Recommended land dimensions for typical chip capacitors

- Multilayer Ceramic Capacitors : Recommended land dimensions (unit: mm)
 Wave-soldering

Type	107	212	316	325	
Size	L	1.6	2.0	3.2	3.2
	W	0.8	1.25	1.6	2.5
A	0.8 to 1.0	1.0 to 1.4	1.8 to 2.5	1.8 to 2.5	
B	0.5 to 0.8	0.8 to 1.5	0.8 to 1.7	0.8 to 1.7	
C	0.6 to 0.8	0.9 to 1.2	1.2 to 1.6	1.8 to 2.5	

Reflow-soldering

Type	042	063	105	107	212	316	325	432
Size	L	0.4	0.6	1.0	1.6	2.0	3.2	4.5
	W	0.2	0.3	0.5	0.8	1.25	1.6	2.5
A	0.15 to 0.25	0.20 to 0.30	0.45 to 0.55	0.8 to 1.0	0.8 to 1.2	1.8 to 2.5	1.8 to 2.5	2.5 to 3.5
B	0.15 to 0.20	0.20 to 0.30	0.40 to 0.50	0.6 to 0.8	0.8 to 1.2	1.0 to 1.5	1.0 to 1.5	1.5 to 1.8
C	0.15 to 0.30	0.25 to 0.40	0.45 to 0.55	0.6 to 0.8	0.9 to 1.6	1.2 to 2.0	1.8 to 3.2	2.3 to 3.5

Note : Recommended land size might be different according to the allowance of the size of the product.

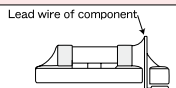
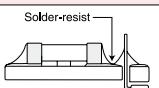
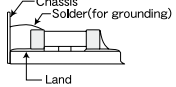
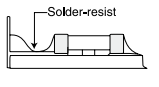
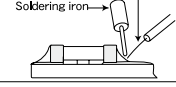
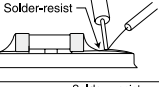
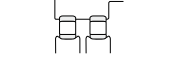

- LWDC: Recommended land dimensions for reflow-soldering (unit: mm)

Type	105	107	212	
Size	L	0.52	0.8	1.25
	W	1.0	1.6	2.0
A	0.18 to 0.22	0.25 to 0.3	0.5 to 0.7	
B	0.2 to 0.25	0.3 to 0.4	0.4 to 0.5	
C	0.9 to 1.1	1.5 to 1.7	1.9 to 2.1	

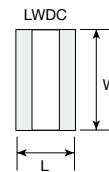
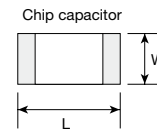
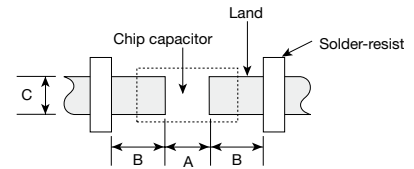
- Array type: Recommended land dimensions for reflow-soldering (unit: mm)

Type	096 (2 circuits)	110 (2 circuits)	212 (2 circuits)	212 (4 circuits)	
Size	L	0.9	1.37	2.0	2.0
	W	0.6	1.0	1.25	1.25
a	0.25 to 0.35	0.35 to 0.45	0.5 to 0.6	0.5 to 0.6	
b	0.15 to 0.25	0.55 to 0.65	0.5 to 0.6	0.5 to 0.6	
c	0.15 to 0.25	0.3 to 0.4	0.5 to 0.6	0.2 to 0.3	
d	0.45	0.64	1.0	0.5	

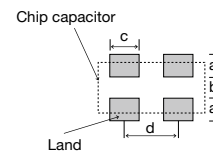
(2) Examples of good and bad solder application

Items	Not recommended	Recommended
Mixed mounting of SMD and leaded components		
Component placement close to the chassis		
Hand-soldering of leaded components near mounted components		
Horizontal component placement		

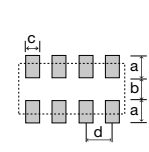
Land patterns for PCBs



2 circuits



4 circuits



To next page

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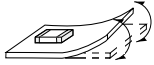
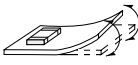
PRECAUTIONS

Precautions on the use of Multilayer Ceramic Capacitors

2. PCB Design

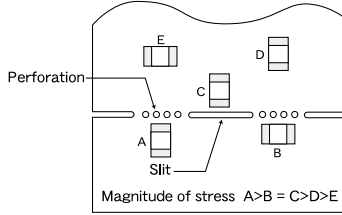
◆Pattern configurations (Capacitor layout on PCBs)

1-1. The following is examples of good and bad capacitor layouts ; capacitors shall be located to minimize any possible mechanical stresses from board warp or deflection.

Items	Not recommended	Recommended
Deflection of board		 Position the component at a right angle to the direction of the mechanical stresses that are anticipated.

Technical considerations

1-2. The amount of mechanical stresses given will vary depending on capacitor layout. Please refer to diagram below.



1-3. When PCB is split, the amount of mechanical stress on the capacitors can vary according to the method used. The following methods are listed in order from least stressful to most stressful: push-back, slit, V-grooving, and perforation. Thus, please consider the PCB, split methods as well as chip location.

3. Mounting

◆Adjustment of mounting machine

- When capacitors are mounted on PCB, excessive impact load shall not be imposed on them.
- Maintenance and inspection of mounting machines shall be conducted periodically.

Precautions

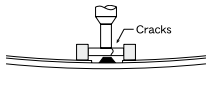
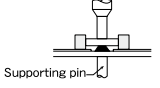
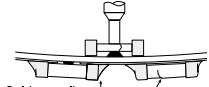
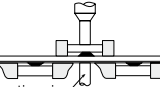
◆Selection of Adhesives

- When chips are attached on PCBs with adhesives prior to soldering, it may cause capacitor characteristics degradation unless the following factors are appropriately checked : size of land patterns, type of adhesive, amount applied, hardening temperature and hardening period. Therefore, please contact us for further information.

◆Adjustment of mounting machine

- When the bottom dead center of a pick-up nozzle is too low, excessive force is imposed on capacitors and causes damages. To avoid this, the following points shall be considerable.

- The bottom dead center of the pick-up nozzle shall be adjusted to the surface level of PCB without the board deflection.
- The pressure of nozzle shall be adjusted between 1 and 3 N static loads.
- To reduce the amount of deflection of the board caused by impact of the pick-up nozzle, supporting pins or back-up pins shall be used on the other side of the PCB. The following diagrams show some typical examples of good and bad pick-up nozzle placement:

Items	Not recommended	Recommended
Single-sided mounting	 Cracks	 Supporting pin
Double-sided mounting	 Solder peeling Cracks	 Supporting pin

Technical considerations

- As the alignment pin is worn out, adjustment of the nozzle height can cause chipping or cracking of capacitors because of mechanical impact on the capacitors. To avoid this, the monitoring of the width between the alignment pins in the stopped position, maintenance, check and replacement of the pin shall be conducted periodically.

◆Selection of Adhesives

Some adhesives may cause IR deterioration. The different shrinkage percentage of between the adhesive and the capacitors may result in stresses on the capacitors and lead to cracking. Moreover, too little or too much adhesive applied to the board may adversely affect components. Therefore, the following precautions shall be noted in the application of adhesives.

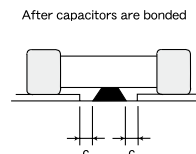
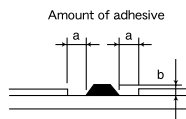
(1) Required adhesive characteristics

- The adhesive shall be strong enough to hold parts on the board during the mounting & solder process.
- The adhesive shall have sufficient strength at high temperatures.
- The adhesive shall have good coating and thickness consistency.
- The adhesive shall be used during its prescribed shelf life.
- The adhesive shall harden rapidly.
- The adhesive shall have corrosion resistance.
- The adhesive shall have excellent insulation characteristics.
- The adhesive shall have no emission of toxic gasses and no effect on the human body.

- The recommended amount of adhesives is as follows;

[Recommended condition]

Figure	212/316 case sizes as examples
a	0.3mm min
b	100 to 120 μ m
c	Adhesives shall not contact land



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Precautions on the use of Multilayer Ceramic Capacitors

4. Soldering

Precautions

◆ Selection of Flux

Since flux may have a significant effect on the performance of capacitors, it is necessary to verify the following conditions prior to use:
 (1) Flux used shall be less than or equal to 0.1 wt% (in Cl equivalent) of halogenated content. Flux having a strong acidity content shall not be applied.
 (2) When shall capacitors are soldered on boards, the amount of flux applied shall be controlled at the optimum level.
 (3) When water-soluble flux is used, special care shall be taken to properly clean the boards.

◆ Soldering

Temperature, time, amount of solder, etc. shall be set in accordance with their recommended conditions.
 Sn-Zn solder paste can adversely affect MLCC reliability.
 Please contact us prior to usage of Sn-Zn solder.

◆ Selection of Flux

1-1. When too much halogenated substance (Chlorine, etc.) content is used to activate flux, or highly acidic flux is used, it may lead to corrosion of terminal electrodes or degradation of insulation resistance on the surfaces of the capacitors.

1-2. Flux is used to increase solderability in wave soldering. However if too much flux is applied, a large amount of flux gas may be emitted and may adversely affect the solderability. To minimize the amount of flux applied, it is recommended to use a flux-bubbling system.

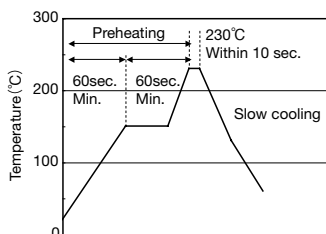
1-3. Since the residue of water-soluble flux is easily dissolved in moisture in the air, the residues on the surfaces of capacitors in high humidity conditions may cause a degradation of insulation resistance and reliability of the capacitors. Therefore, the cleaning methods and the capability of the machines used shall also be considered carefully when water-soluble flux is used.

◆ Soldering

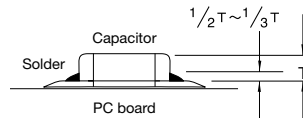
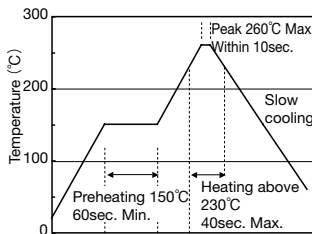
- Ceramic chip capacitors are susceptible to thermal shock when exposed to rapid or concentrated heating or rapid cooling.
- Therefore, the soldering must be conducted with great care so as to prevent malfunction of the components due to excessive thermal shock.
- Preheating : Capacitors shall be preheated sufficiently, and the temperature difference between the capacitors and solder shall be within 100 to 130°C.
- Cooling : The temperature difference between the capacitors and cleaning process shall not be greater than 100°C.

[Reflow soldering]

[Recommended conditions for eutectic soldering]



[Recommended condition for Pb-free soldering]



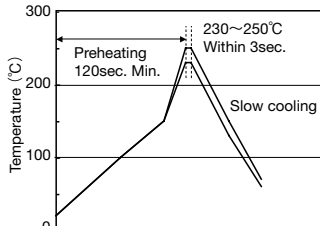
Caution

- ① The ideal condition is to have solder mass (fillet) controlled to 1/2 to 1/3 of the thickness of a capacitor.
- ② Because excessive dwell times can adversely affect solderability, soldering duration shall be kept as close to recommended times as possible.

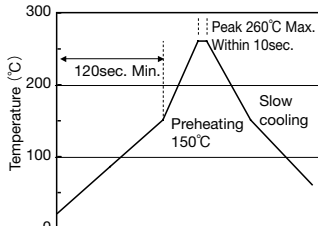
Technical considerations

[Wave soldering]

[Recommended conditions for eutectic soldering]



[Recommended condition for Pb-free soldering]

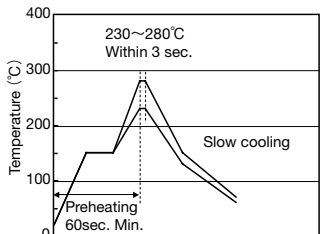


Caution

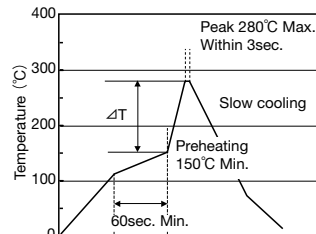
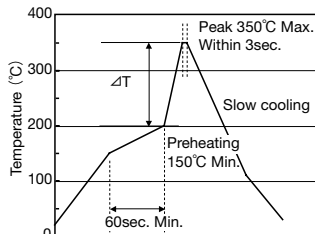
- ① Wave soldering must not be applied to capacitors designated as for reflow soldering only.

[Hand soldering]

[Recommended conditions for eutectic soldering]



[Recommended condition for Pb-free soldering]



Caution

- ① Use a 50W soldering iron with a maximum tip diameter of 1.0 mm.
- ② The soldering iron shall not directly touch capacitors.

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PRECAUTIONS

Precautions on the use of Multilayer Ceramic Capacitors

5. Cleaning	
Precautions	<ul style="list-style-type: none">◆Cleaning conditions1. When PCBs are cleaned after capacitors mounting, please select the appropriate cleaning solution in accordance with the intended use of the cleaning. (e.g. to remove soldering flux or other materials from the production process.)2. Cleaning condition shall be determined after it is verified by using actual cleaning machine that the cleaning process does not affect capacitor's characteristics.
Technical considerations	<ul style="list-style-type: none">1. The use of inappropriate cleaning solutions can cause foreign substances such as flux residue to adhere to capacitors or deteriorate their outer coating, resulting in a degradation of the capacitor's electrical properties (especially insulation resistance).2. Inappropriate cleaning conditions (insufficient or excessive cleaning) may adversely affect the performance of the capacitors. In the case of ultrasonic cleaning, too much power output can cause excessive vibration of PCBs which may lead to the cracking of capacitors or the soldered portion, or decrease the terminal electrodes' strength. Therefore, the following conditions shall be carefully checked; Ultrasonic output : 20 W/l or less Ultrasonic frequency : 40 kHz or less Ultrasonic washing period : 5 min. or less
6. Resin coating and mold	
Precautions	<ul style="list-style-type: none">1. With some type of resins, decomposition gas or chemical reaction vapor may remain inside the resin during the hardening period or while left under normal storage conditions resulting in the deterioration of the capacitor's performance.2. When a resin's hardening temperature is higher than capacitor's operating temperature, the stresses generated by the excessive heat may lead to damage or destruction of capacitors. The use of such resins, molding materials etc. is not recommended.
7. Handling	
Precautions	<ul style="list-style-type: none">◆Splitting of PCB1. When PCBs are split after components mounting, care shall be taken so as not to give any stresses of deflection or twisting to the board.2. Board separation shall not be done manually, but by using the appropriate devices.◆Mechanical considerationsBe careful not to subject capacitors to excessive mechanical shocks. (1) If ceramic capacitors are dropped onto a floor or a hard surface, they shall not be used. (2) Please be careful that the mounted components do not come in contact with or bump against other boards or components.
8. Storage conditions	
Precautions	<ul style="list-style-type: none">◆Storage1. To maintain the solderability of terminal electrodes and to keep packaging materials in good condition, care must be taken to control temperature and humidity in the storage area. Humidity should especially be kept as low as possible.<ul style="list-style-type: none">•Recommended conditionsAmbient temperature : Below 30°CHumidity : Below 70% RHThe ambient temperature must be kept below 40°C. Even under ideal storage conditions, solderability of capacitor is deteriorated as time passes, so capacitors shall be used within 6 months from the time of delivery.<ul style="list-style-type: none">•Ceramic chip capacitors shall be kept where no chlorine or sulfur exists in the air.2. The capacitance values of high dielectric constant capacitors will gradually decrease with the passage of time, so care shall be taken to design circuits. Even if capacitance value decreases as time passes, it will get back to the initial value by a heat treatment at 150°C for 1hour.
Technical considerations	If capacitors are stored in a high temperature and humidity environment, it might rapidly cause poor solderability due to terminal oxidation and quality loss of taping/packaging materials. For this reason, capacitors shall be used within 6 months from the time of delivery. If exceeding the above period, please check solderability before using the capacitors.

※RCR-2335B (Safety Application Guide for fixed ceramic capacitors for use in electronic equipment) is published by JEITA.
Please check the guide regarding precautions for deflection test, soldering by spot heat, and so on.